National Semiconductor

October 1999

54FCT373
Octal Transparent Latch with TRI-STATE® Outputs

General Description

The 'FCT373 consists of eight latches with TRI-STATE outputs for bus organized system applications. The flip-flops appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup times is latched. Data appears on the bus when the Output Enable ($\overline{OE}$) is LOW. When $\overline{OE}$ is HIGH the bus output is in the high impedance state.

Features

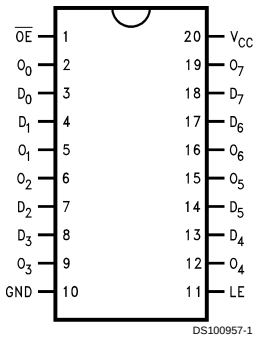
- TRI-STATE outputs for bus interfacing
- TTL input and output level compatible
- CMOS power consumption
- Output sink capability of 32 mA, source capability of 12 mA
- Standard Microcircuit Drawing (SMD) 5962-8764401

Ordering Code

Military	Package Number	Package Description
54FCT373DMQB	J20A	20-Lead Ceramic Dual-In-Line
54FCT373FMQB	W20A	20-Lead Cerpack
54FCT373LMQB	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

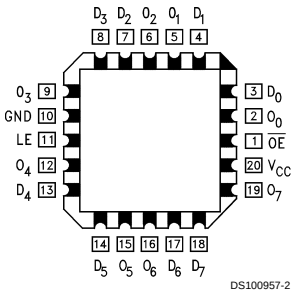
Connection Diagrams

Pin Assignment for DIP and Flatpak



DS100957-1

Pin Assignment for LCC



DS100957-2

Pin Names	Description
D_0–D_7	Data Inputs
LE	Latch Enable Input (Active HIGH)
$\overline{OE}$	Output Enable Input (Active LOW)
O_0–O_7	TRI-STATE Latch Outputs

TRI-STATE® is a registered trademark of National Semiconductor Corporation.

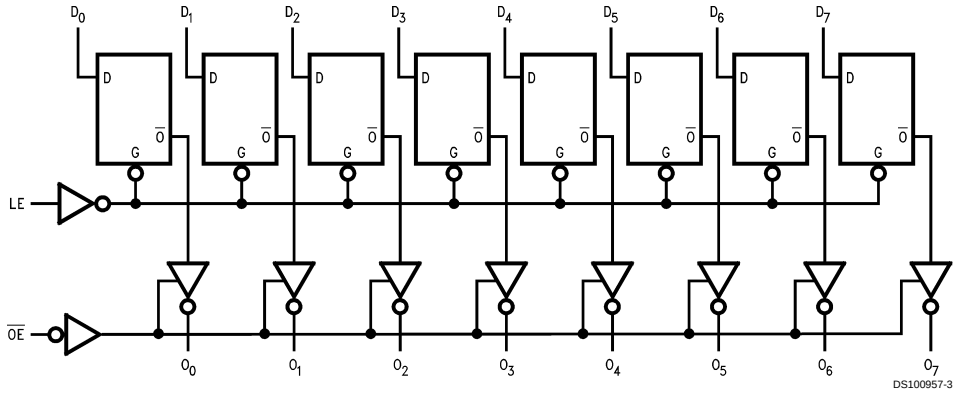
Functional Description

The 'FCT373 contains eight D-type latches with TRI-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D input changes. When LE is LOW, the latches store the information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LE. The TRI-STATE buffers are controlled by the Output Enable ($\overline{OE}$) input. When $\overline{OE}$ is LOW, the buffers are in the bi-state mode. When $\overline{OE}$ is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

Inputs			Output
LE	$\overline{OE}$	D_n	O_n
H	L	H	H
H	L	L	L
L	L	X	O_n (no change)
X	H	X	Z

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance State

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Storage Temperature	−65˚C to +150˚C
Ambient Temperature under Bias	−55˚C to +125˚C
Junction Temperature under Bias Ceramic	−55˚C to +175˚C
V_{CC} Pin Potential to Ground Pin	−0.5V to +7.0V
Input Voltage (Note 2)	−0.5V to +7.0V
Input Current (Note 2)	−30 mA to +5.0 mA
Voltage Applied to Any Output in the Disabled or Power-Off State	−0.5V to +5.5V
in the HIGH State	−0.5V to V_{CC}
Current Applied to Output in LOW State (Max)	twice the rated I_{OL} (mA)

Recommended Operating Conditions

Free Air Ambient Temperature Military	−55˚C to +125˚C
Supply Voltage Military	+4.5V to +5.5V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parameter		FCT240 Min	FCT240 Max	Units	V_{CC}	Conditions
V_{IH}	Input HIGH Voltage		2.0		V		Recognized HIGH Signal
V_{IL}	Input LOW Voltage			0.8	V		Recognized LOW Signal
V_{CD}	Input Clamp Diode Voltage			−1.2	V	Min	I_{IN} = −18 mA
V_{OH}	Output HIGH Voltage	54FCT	4.3		V	Min	I_{OH} = −300 uA
		54FCT	2.4		V	Min	I_{OH} = −12 mA
V_{OL}	Output LOW Voltage	54FCT		0.2	V	Min	I_{OL} = 300 µA
		54FCT		0.5	V	Min	I_{OL} = 32 mA
I_{IH}	Input HIGH Current			5	µA	Max	V_{IN} = 5.5V
I_{IL}	Input LOW Current			−5	µA	Max	V_{IN} = 0.0V
I_{OZH}	High Impedance Output Current			10	µA	Max	V_{IN} = 5.5V
I_{OZL}	High Impedance Output Current			-10	µA	Max	V_{IN} = 0.0V
I_{OS}	Output Short-Circuit Current			−60	mA	Max	V_{OUT} = 0.0V
I_{CCQ}	Power Supply Current			1.5	mA	Max	V_{IN} = 0.2V or V_{IN} = 5.3V
ΔI_{CC}	Power Supply Current			2.0	mA	Max	V_{IN} = 3.4V
I_{CCT}	Total Power Supply Current			5.6	mA	Max	V_{IN} = 3.4V or V_{IN} =GND, $\overline{OE}$ = GND, f_i = 10Mhz, outputs open, one bit toggling, 50% duty cycle
				4.0	mA	Max	V_{IN} = 5.3V or V_{IN} = 0.2V,$\overline{OE}$ = GND, f_i = 10Mhz, outputs open, one bit toggling, 50% duty cycle
I_{CCD}	Dynamic I_{CC}			0.25	mA/MHz	Max	Outputs Open, $\overline{OE}$ = GND, one bit toggling, 50% duty Cycle

AC Electrical Characteristics

Symbol	Parameter	54FCT $T_A = -55^\circ C$ to $+125^\circ C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 50$ pF		Units	Fig. No.
		Min	Max		
t_{PLH}	Propagation Delay	1.5	8.5	ns	*Figure 4*
t_{PHL}	D_n to O_n	1.5	8.5		
t_{PLH}	Propagation Delay	2.0	15.0	ns	*Figure 4*
t_{PHL}	LE to O_n	2.0	15.0		
t_{PZH}	Output Enable Time	1.5	13.5	ns	*Figure 6*
t_{PZL}		1.5	13.5		
t_{PHZ}	Output Disable Time	1.5	12.5	ns	*Figure 6*
t_{PLZ}		1.5	12.5		

AC Operating Requirements

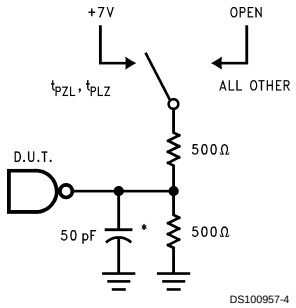
Symbol	Parameter	54FCT $T_A = -55^\circ C$ to $+125^\circ C$, $V_{CC} = 4.5V$ to $5.5V$, $C_L = 50$ pF		Units	Fig. No.
		Min	Max		
$t_s(H)$	Setup Time, HIGH	2.0		ns	*Figure 7*
$t_s(L)$	or LOW D_n to LE	2.0			
$t_h(H)$	Hold Time, HIGH	3.0		ns	*Figure 7*
$t_h(L)$	or LOW D_n to LE	3.0			
$t_w(H)$	Pulse Width, LE HIGH	6.0		ns	*Figure 5*

Capacitance

Symbol	Parameter	Max	Units	Conditions ($T_A = 25^\circ C$)
C_{IN}	Input Capacitance	10	pF	$V_{CC} = 0V$
C_{OUT} (Note 3)	Output Capacitance	12	pF	$V_{CC} = 5.0V$

Note 3: C_{OUT} is measured at frequency f = 1 MHz, per MIL-STD-883B, Method 3012.

AC Loading



*Includes jig and probe capacitance

FIGURE 1. Standard AC Test Load

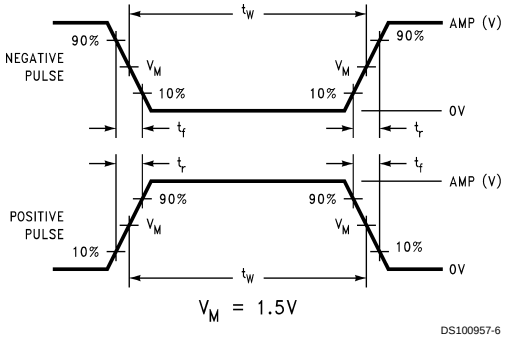


FIGURE 2. Test Input Signal Levels

Amplitude	Rep. Rate	t_w	t_r	t_f
3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

FIGURE 3. Test Input Signal Requirements

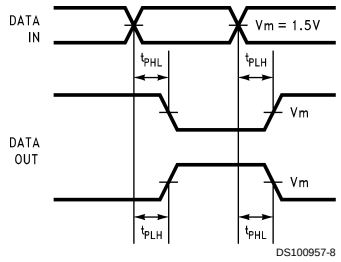


FIGURE 4. Propagation Delay Waveforms for Inverting and Non-Inverting Functions

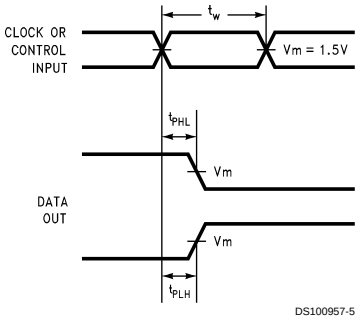


FIGURE 5. Propagation Delay, Pulse Width Waveforms

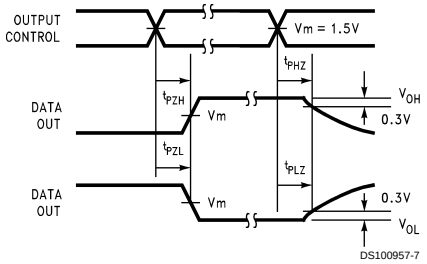


FIGURE 6. TRI-STATE Output HIGH and LOW Enable and Disable Times

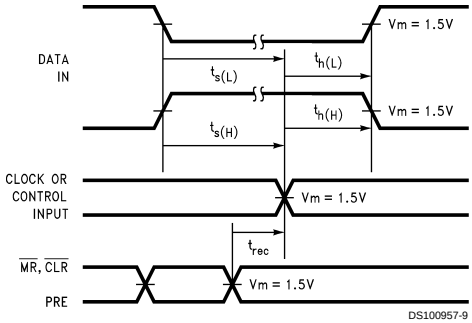
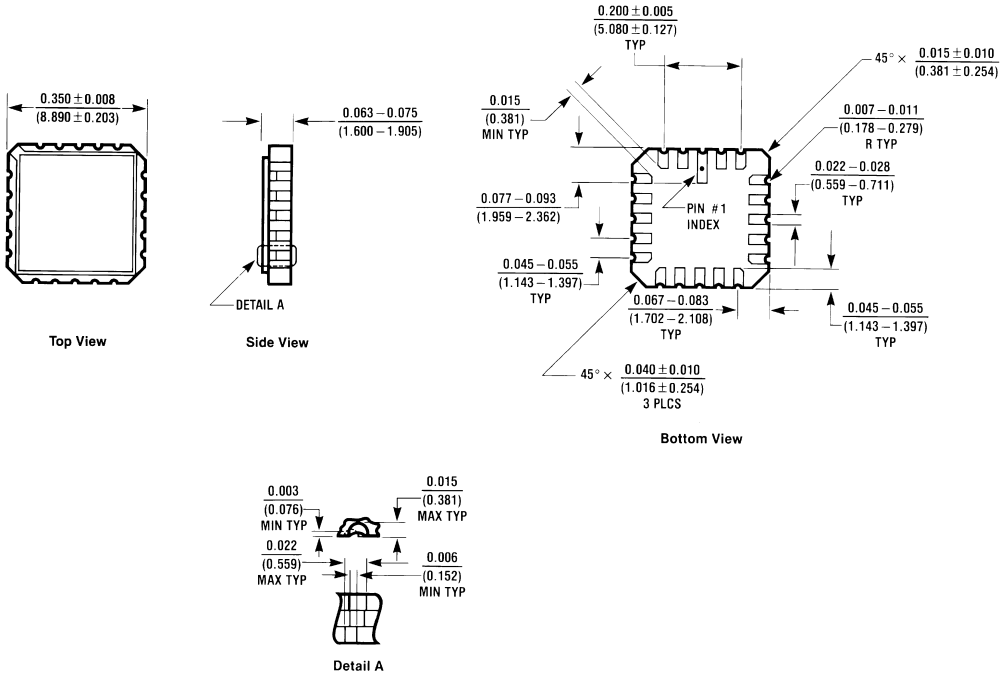


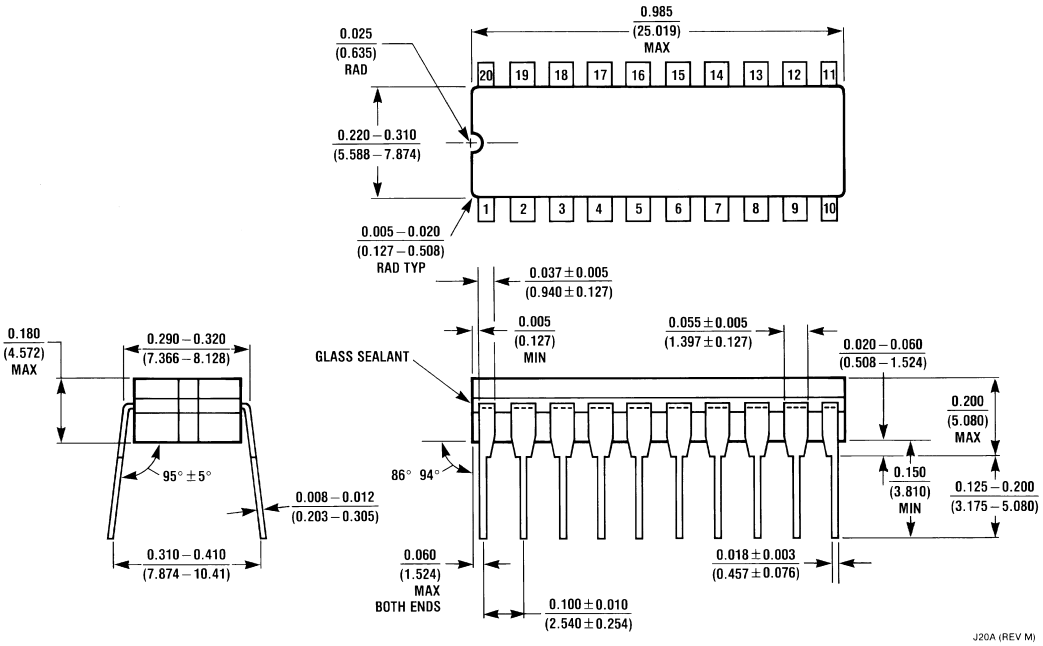
FIGURE 7. Setup Time, Hold Time and Recovery Time Waveforms

Physical Dimensions inches (millimeters) unless otherwise noted

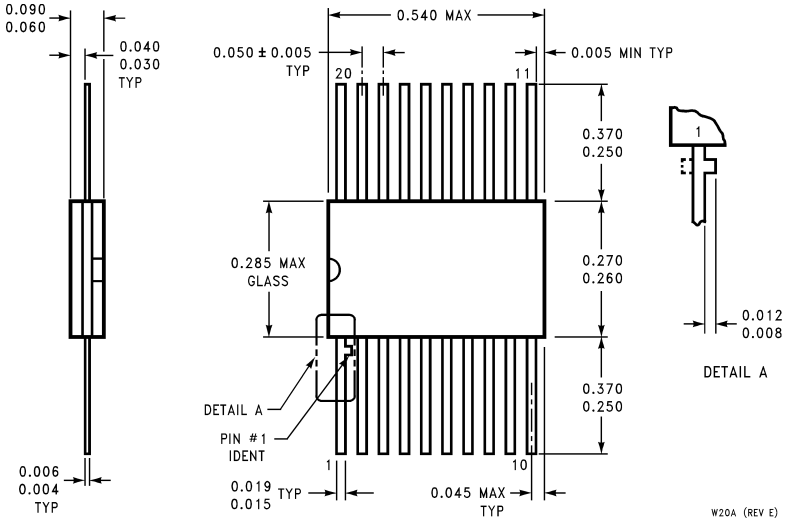


20-Terminal Ceramic Chip Carrier (L)
NS Package Number E20A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Ceramic Dual-In-Line (D)
NS Package Number J20A



20-Lead Ceramic Flatpak (F)
NS Package Number W20A

Notes

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

National Semiconductor Corporation
Americas
Tel: 1-800-272-9959
Fax: 1-800-737-7018
Email: support@nsc.com

www.national.com

National Semiconductor Europe
Fax: +49 (0) 1 80-530 85 86
Email: europe.support@nsc.com
Deutsch Tel: +49 (0) 1 80-530 85 85
English Tel: +49 (0) 1 80-532 78 32
Français Tel: +49 (0) 1 80-532 93 58
Italiano Tel: +49 (0) 1 80-534 16 80

National Semiconductor Asia Pacific Customer Response Group
Tel: 65-2544466
Fax: 65-2504466
Email: sea.support@nsc.com

National Semiconductor Japan Ltd.
Tel: 81-3-5639-7560
Fax: 81-3-5639-7507